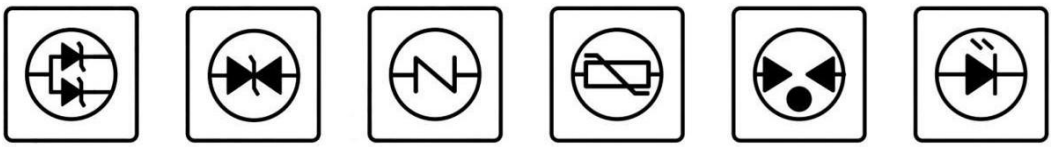
MSKSEMI 美森科
SEMICONDUCTOR

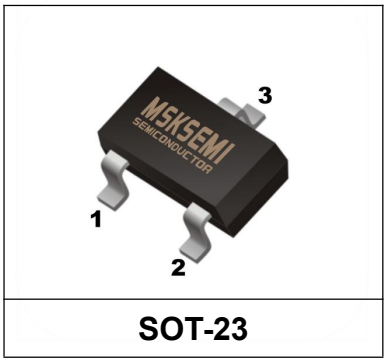


BAS21/A/C/S

Product specification

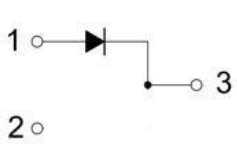
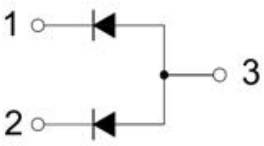
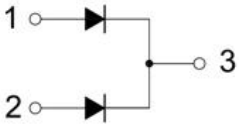
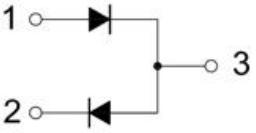
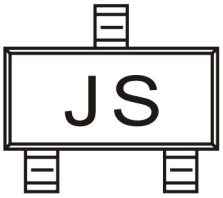
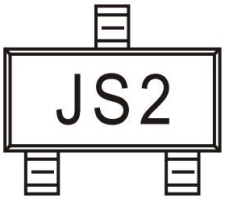
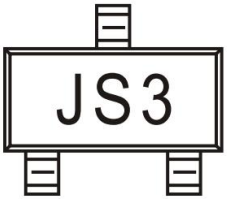
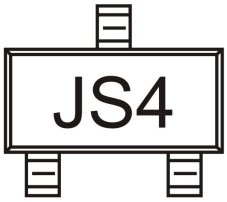
Features

- Fast Switching Speed
- Surface Mount Package Ideally Suited for Automatic Insertion
- For General Purpose Switching Applications
- High Conductance



SOT-23

Reference News

Pin Configuration				
Marking				
P/N	**BAS21**	**BAS21A**	**BAS21C**	**BAS21S**

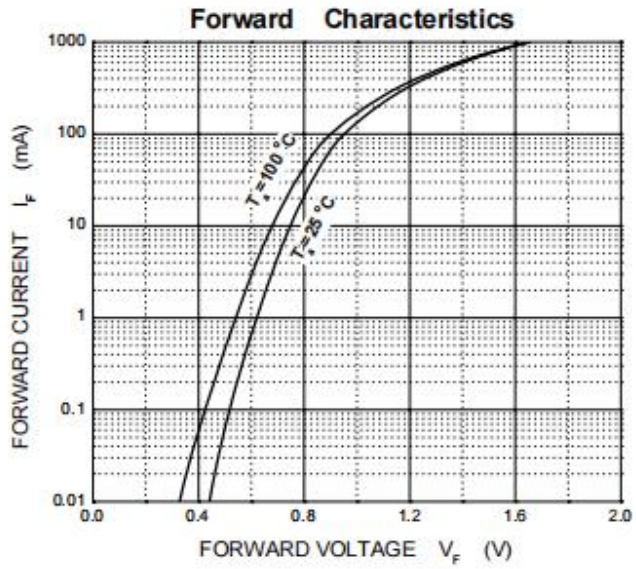
Maximum Ratings @Ta=25℃

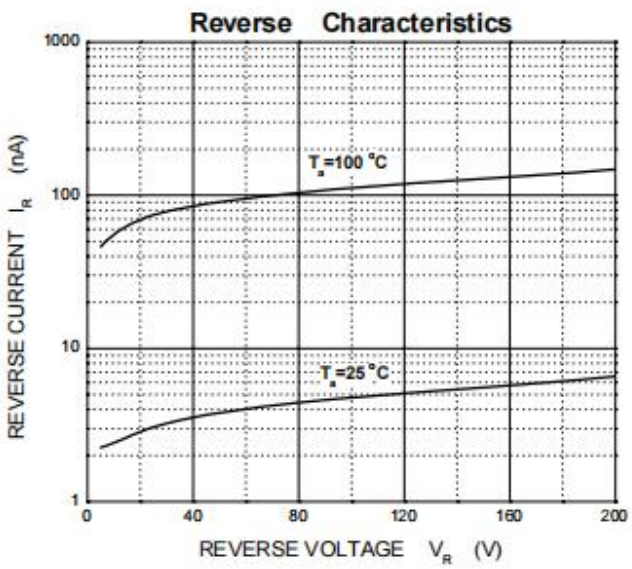
Parameter	Symbol	Limit	Unit
Repetitive peak reverse voltage Working peak reverse voltage DC blocking voltage	V_{RRM} V_{RWM} V_R	250	V
Forward continuous current	I_{FM}	400	mA
Average rectified output current	I_O	200	mA
Non-Repetitive Peak Forward Surge Current @t=8.3ms	I_{FSM}	2.5	A
Repetitive peak forward surge current	I_{FRM}	625	mA
Power dissipation	P_D	225	mW
Thermal resistance junction to ambient	$R_{\theta JA}$	555	℃/W
Junction temperature	T_J	150	℃
Storage temperature range	T_{STG}	-55~+150	℃

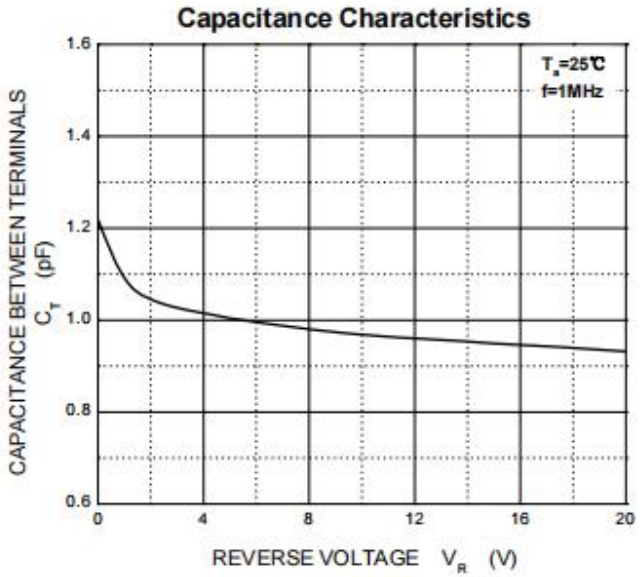
ELECTRICAL CHARACTERISTICS (Ta=25℃ unless otherwise specified)

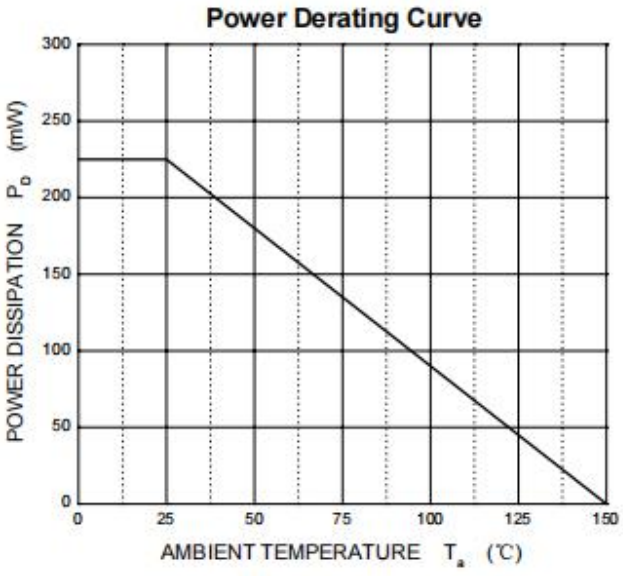
Parameter	Symbol	Test conditions	Min	Max	Unit
Reverse breakdown voltage	$V_{(BR)}$	I_R= 100μA	250		V
Reverse voltage leakage current	I_R	V_R = 200V		0.1	μA
Forward voltage	V_F	I_F=100mA I_F=200mA		1000 1250	mV
Diode capacitance	C_D	V_R=0V, f=1MHz		5	pF
Reveres recovery time	t_{rr}	I_F=I_R=30mA,I_{rr}=0. 1×I_R, R_L=100Ω		50	ns

Typical Characteristics

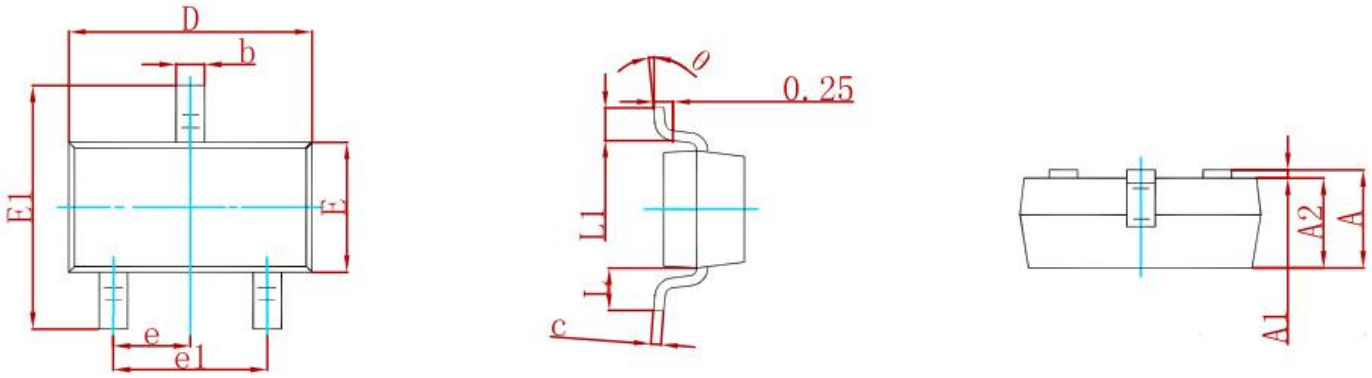






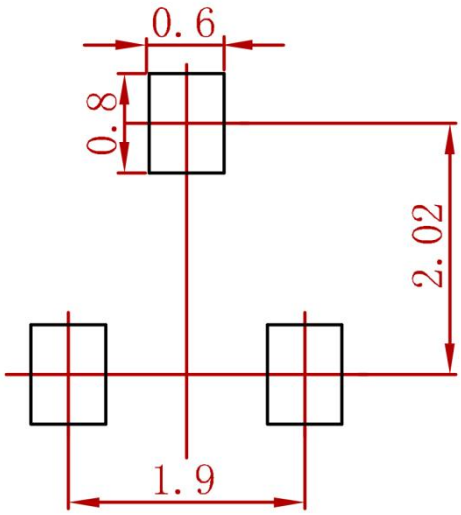


PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

Suggested Pad Layout



Note:

1.Controlling dimension:in millimeters.

2.General tolerance:±0.05mm.

3.The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
BAS21/A/C/S	SOT-23	3000

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